

Electronic Acknowledgement Receipt

EFS ID:	1218975
Application Number:	10772345
Confirmation Number:	5051
Title of Invention:	Lead frame, resin sealing mold and method for manufacturing a semiconductor device using the same
First Named Inventor:	Isao Ochiai
Customer Number:	52190
Filer:	Stephen B. Parker
Filer Authorized By:	
Attorney Docket Number:	2905-107
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Drawings	DrawingRESubmission.pdf	48682	no	1

Warnings:							
Information:							
2	Drawings	ResubmittedDrawings.pdf	259746	no	2		
Warnings:							
Information:							
Total Files Size (in bytes):				308428			
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<p>New Applications Under 35 U.S.C. 111 If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p>							
<p>National Stage of an International Application under 35 U.S.C. 371 If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p>							